Title (en)

Process for preparing a sintered hard metal, and sintered hard metal obtained thereby.

Title (de)

Verfahren zur Herstellung eines gesinterten Hartmetallkörpers und gesinterter Hartmetallkörper.

Title (fr)

Procédé de préparation d'un métal dur fritté et métal dur fritté ainsi obtenu.

Publication

EP 0330913 A2 19890906 (DE)

Application

EP 89102623 A 19890216

Priority

DE 3806602 A 19880302

Abstract (en)

To improve the heat resistant properties of sintered hard metals, in particular with a view to achieving greater cutting powers during use as the cutting tool, it is proposed to alloy aluminium-containing complex nitrides and/or aluminium-containing complex carbides, in particular from the family comprising the H, chi or kappa phases, with the binder metal to which at least one hard material phase has been added.

Abstract (de)

Zur Verbesserung der Warmfestigkeitseigenschaften von Sinterhartmetallen, insbesondere im Hinblick auf die Erzielung höherer Schnittleistungen bei Verwendung als Schneidwerkzeug, wird der Vorschlag unterbreitet, dem mit zumindest einer Hartstoffphase versetzten Bindermetall aluminiumhaltige Komplexnitride und/oder aluminiumhaltige Komplexcarbide, insbesondere aus der Familie der H-, Chi- oder Kappa-Phasen, zuzulegieren.

IPC 1-7

C22C 1/05

IPC 8 full level

C22C 1/05 (2006.01); **C22C 29/02** (2006.01); **C22C 29/04** (2006.01); **C22C 29/06** (2006.01); **C22C 29/08** (2006.01); **C22C 29/10** (2006.01); **C22C 29/16** (2006.01); **C22C 32/00** (2006.01)

CPC (source: EP US)

C22C 1/051 (2013.01 - EP US); **C22C 1/058** (2023.01 - EP US); **C22C 19/00** (2013.01 - EP US); **C22C 29/02** (2013.01 - EP US); **C22C 33/02** (2013.01 - EP US); B22F 2998/00 (2013.01 - EP US)

Designated contracting state (EPC)

AT CH DE ES FR GB IT LI NL SE

DOCDB simple family (publication)

US 4944800 A 19900731; AT E89329 T1 19930515; DD 279031 A5 19900523; DE 3806602 A1 19880707; DE 3806602 C2 19910404; DE 58904302 D1 19930617; EP 0330913 A2 19890906; EP 0330913 A3 19900613; EP 0330913 B1 19930512; ES 2054893 T3 19940816; JP H01294842 A 19891128; JP H0711042 B2 19950208

DOCDB simple family (application)

US 31817789 A 19890302; AT 89102623 T 19890216; DD 32609089 A 19890228; DE 3806602 A 19880302; DE 58904302 T 19890216; EP 89102623 A 19890216; ES 89102623 T 19890216; JP 4866389 A 19890302